TOP MARK INFORMATION
(Not all marks shown may appear on parts)

883 & 36510 Date Code
2nd digit:  Last digit of the year wafer sort was performed.
3rd digit:  Alpha character indicating the calendar
           quarter in which wafer sort was performed.
           Character   Months    Weeks
           A           Jan-Mar    1-13
           B           Apr-Jun     14-26
           C           Jul-Sep     27-39
           D           Oct-Dec     40-53
           GF          Prior to 1988

4th & 5th digits:  Calendar year
6th & 7th digits:  Sealweek
8th digits:  Alpha character indicating the lot is a sub-lot
             (when applicable).

Worldmark**
Products available
to DSCC Drawings
may be Dual Marked ***

Pin 1 Orientation
or

IC Package Types
D    Glass/Metal DIP
DM   Ceramic DIP
F    Glass/Metal Flatpak (14x14)
FM   Flat pack
G    12 Lead TO-8 CAN
H    Multi-Lead CAN
J    Lo-Temp Ceramic DIP
     (‘Fit-Seal’ Package)
J-8  8 Lead Ceramic DIP
     (MiniDIP Package)
K    TO-3 CAN in Steel, except LM300K
     which is shipped in Aluminium
Ks   TO-3 CAN (Steel)
L    Ceramic Leaded Chip Carrier
LM   Ceramic Leadless Chip Carrier (LCC)
U    Pin Grid Array
W    Lo-Temp Ceramic Flatpack
WG   Ceramic SOIC

Military Electrostatic
Discharge (ESD)
Sensitivity Indicator
Mark   Class Voltage
\( \triangle \)  1  0-1500V
\( \triangle \triangle \) 2  2000-3000V
\( \Delta \)  3  \( \geq \) 4000V

Test site
The test site codes are
the same as the plant
of Manufacture codes
detailed on this page.
- optional -

QML Compliance Indicator

Part number
Device
suffix
883  Compliant to MIL-STD-883
QB:  MIL-STD-883*
-QML QML
-QMLV Space level QML
-MLS Non QMLV space
-MIL Non compliant B level

Note: Some products using the "QB" designator may not be compliant to

** Parts manufactured before June 1, 1994
may have old logo.
*** Marking in accordance with DSCC conventions.